## SPECIAL PROCEDURES SUBMISSION

**PATENT** 

Docket No. MTI-31607

## IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

**Applicant** 

Lee, Teck Kheng

Serial No.

10/050,507

Filing Date

January 16, 2002

RECEIVED

FEB 0 8 2005

For:

Elimination of RDL Using Tape Base Flip Chip on Flex for Die Stacking FICE OF PETITIONS

Group Art Unit:

2813

Confirmation No.:

7687

Examiner

THOMPSON, Craig

CERTIFICATION UNDER 37 CFR 1.8(a) and 1.10

I hereby certify that, on the date shown below, this correspondence is being hand delivered to OFFICE OF PETITIONS at

the US Patent and Trademark Office.

**OFFICE OF PETITIONS** 

U.S. Patent and Trademark Office 2201 South Clark Place Crystal Plaza 4, Suite 3C23

Arlington, Virginia 22202

## PETITION UNDER 37 CFR §§ 1.313(c)(2) and 1.114

Sir:

Applicant hereby petitions withdrawal of the above-referenced application from issue pursuant to 37 CFR §§ 1.313(c)(2). A Notice of Issue was received indicating the issue date as February 22, 2005, as US Patent No. 6,858,940.

This petition is being made to permit reopening of prosecution for the Examiner to consider references that were cited in a related application but not cited in the present application. Applicant submits herewith a Request for Continued Examination in compliance with § 1.114.

Please charge the Petition fee set forth in 37 CFR § 1.17(h) and the RCE fee set forth in 37 CFR § 1.17(e) to deposit account No. <u>23-2053</u>. The Applicant is a large entity.

The consideration and grant of this petition is earnestly requested.

Respectfully submitted,

Kristini Mstrodyla Kristine M. Strodthoff, Reg. No. 34.259

WHYTE HIRSCHBOECK DUDEK S.C.

555 East Wells Street, Suite 1900 Milwaukee, Wisconsin 53202-3819

(414) 273-2100

Customer No. 31870

Attachments:

No. 34,259

Timents:
Request for Continued Examination
Supplemental Information Disclosure Statement
Form 1449/PTO

10050507

MKE/1011388.1